Description

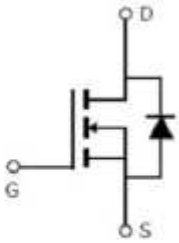
It utilizes the latest processing techniques to achieve the high cell density and reduces the on-resistance with high repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in power switching application and a wide variety of other applications.

Features and Benefits:

- Advanced MOSFET process technology
- Special designed for PWM, load switching and general purpose applications
- Ultra low on-resistance with low gate charge
- Fast switching and reverse body recovery
- 175℃ operating temperature

DPAK

Marking and pin Assignment



Schematic diagram

Main Product Characteristics

V_{DSS}	60V
R_{DS}(on)	12mΩ (typ.)
I_D	60A

Absolute Maximum Ratings

Symbol	Parameter	Max.	Units
I_D @ TC = 25℃	Continuous Drain Current, V_{GS} @ 10V①	60	A
I_D @ TC = 100℃	Continuous Drain Current, V_{GS} @ 10V ①	42	
I_{DM}	Pulsed Drain Current②	240	
P_D @TC = 25℃	Power Dissipation③	115	W
	Linear Derating Factor	0.74	W/℃
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy @ L=0.3mH	235	mJ
I_{AS}	Avalanche Current @ L=0.3mH	39	A
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 175	℃

Thermal Resistance

Symbol	Characteristics	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-case③	—	1.31	℃/W
$R_{\theta JA}$	Junction-to-ambient ④	—	62	℃/W

ELECTRICAL CHARACTERISTICS (T_A=25℃ unless otherwise noted)

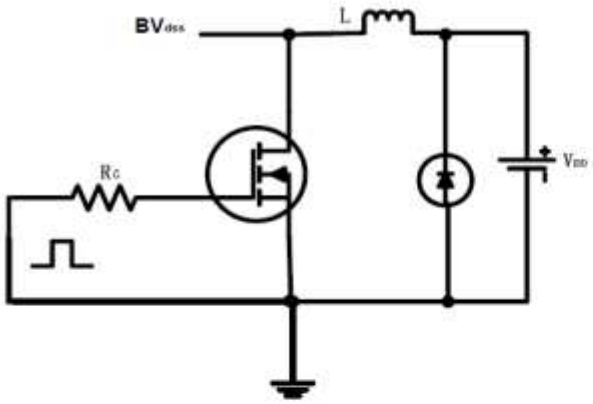
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source breakdown voltage	60	—	—	V	V_{GS} = 0V, I_D = 250μA
$R_{DS(on)}$	Static Drain-to-Source on-resistance	—	12	14	mΩ	V_{GS}=10V,I_D = 30A
$V_{GS(th)}$	Gate threshold voltage	2.0	—	4.0	V	V_{DS} = V_{GS}, I_D =250μA
		—	2.0	—		T_J = 125℃
I_{DSS}	Drain-to-Source leakage current	—	—	2	μA	V_{DS} = 60V,V_{GS} = 0V
		—	—	10		T_J = 150℃
I_{GSS}	Gate-to-Source forward leakage	—	—	100	nA	V_{GS} =20V
		—	—	-100		V_{GS} = -20V
Qg	Total gate charge	—	45	—	nC	I_D = 30A,
Qgs	Gate-to-Source charge	—	4	—		V_{DS}=30V,
Qgd	Gate-to-Drain("Miller") charge	—	15	—		V_{GS} = 10V
td(on)	Turn-on delay time	—	14.6	—	ns	V_{GS}=10V, V_{DS}=30V,
tr	Rise time	—	14.2	—		R_L=15Ω,
td(off)	Turn-Off delay time	—	40	—		R_{GEN}=2.5Ω
tf	Fall time	—	7.3	—		
Ciss	Input capacitance	—	1480	—	pF	V_{GS} = 0V
Coss	Output capacitance	—	190	—		V_{DS} = 25V
Crss	Reverse transfer capacitance	—	135	—		f = 1MHz

Source-Drain Ratings and Characteristics

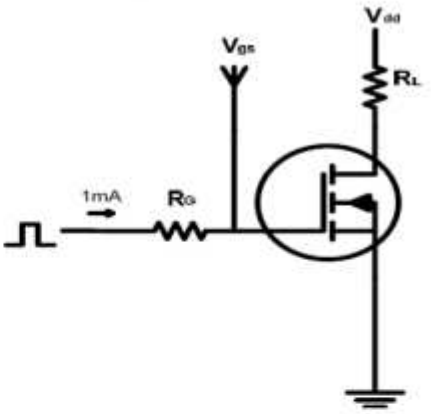
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	60	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode)	—	—	240	A	
V_{SD}	Diode Forward Voltage	—	—	1.3	V	I_S=30A, V_{GS}=0V
trr	Reverse Recovery Time	—	33	—	ns	T_J = 25℃, I_F =15A,
Qrr	Reverse Recovery Charge	—	61	—	nC	di/dt = 100A/μs

Test circuits and Waveforms

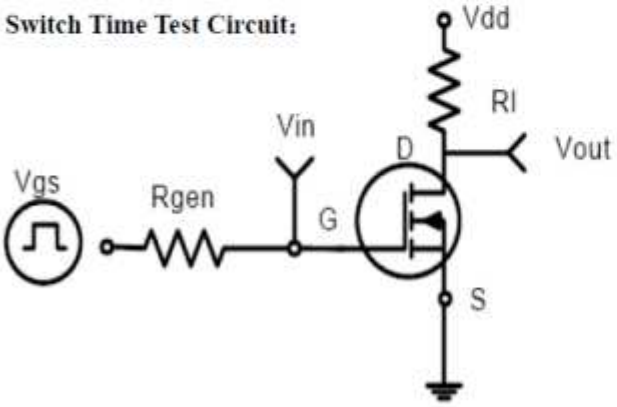
EAS test circuits:



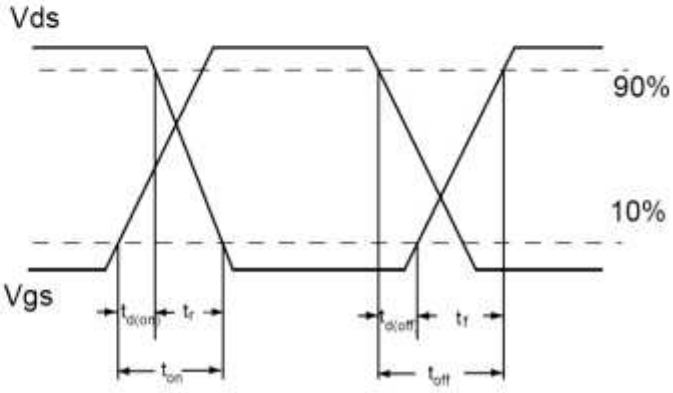
Gate charge test circuit:



Switch Time Test Circuit:



Switch Waveforms:



Notes:

①The maximum current rating is limited by bond-wires.
②Repetitive rating; pulse width limited by max. junction temperature.
③The power dissipation PD is based on max. junction temperature, using junction-to-case thermal resistance.
④The value of $R_{\theta JA}$ is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25℃
⑤These curves are based on the junction-to-case thermal impedence which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=175℃.
⑥ The maximum current rating is limited by bond-wires.

Typical electrical and thermal characteristics

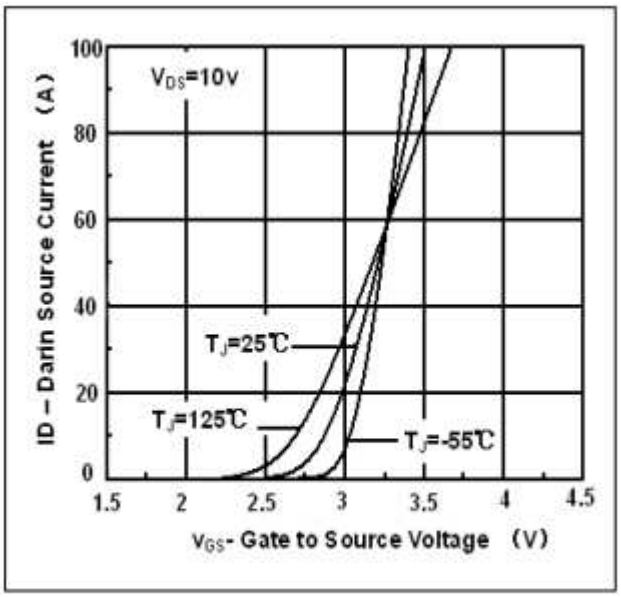


Figure 1,Transfer Characteristic

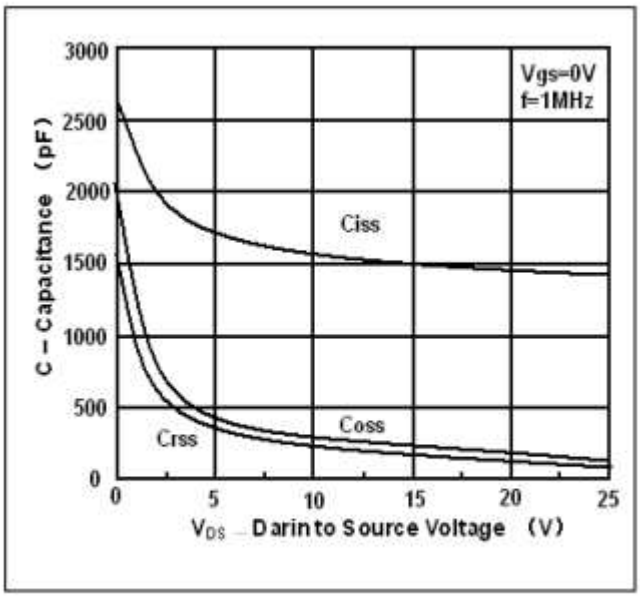


Figure 2,Capacitance

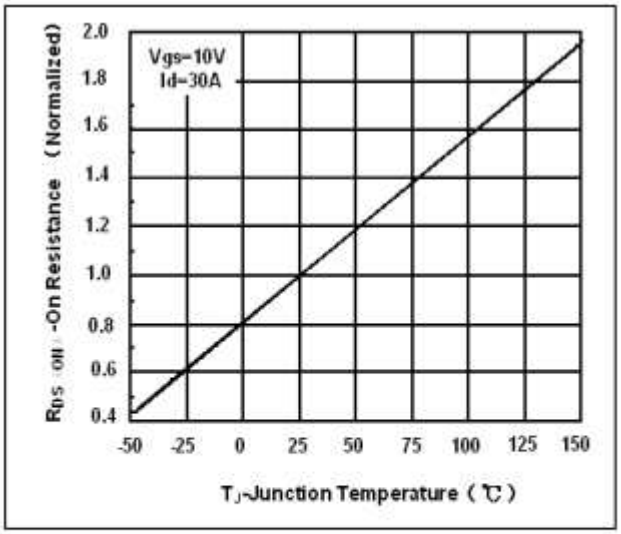


Figure 3,On Resistance vs. Junction Temperature

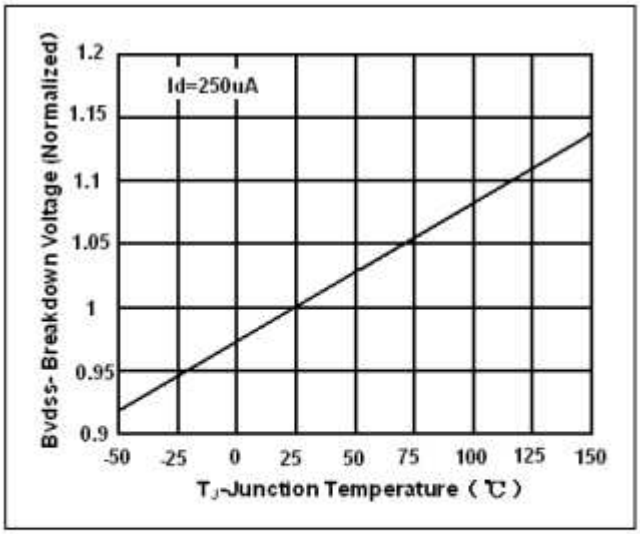


Figure 4,Breakdown Voltage vs. Junction Temperature

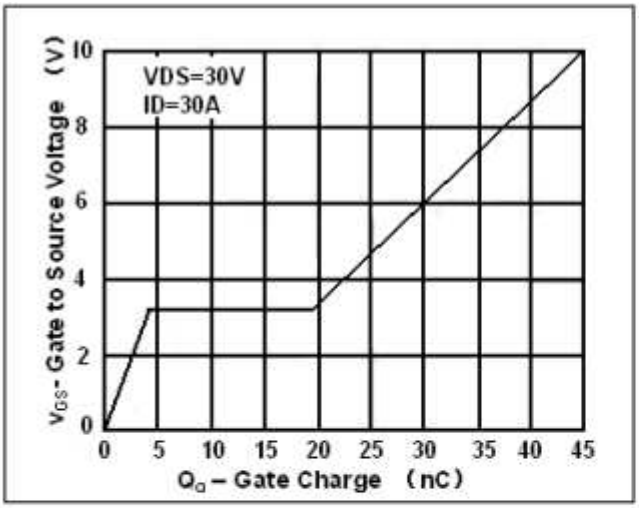


Figure 5,Gate Charge

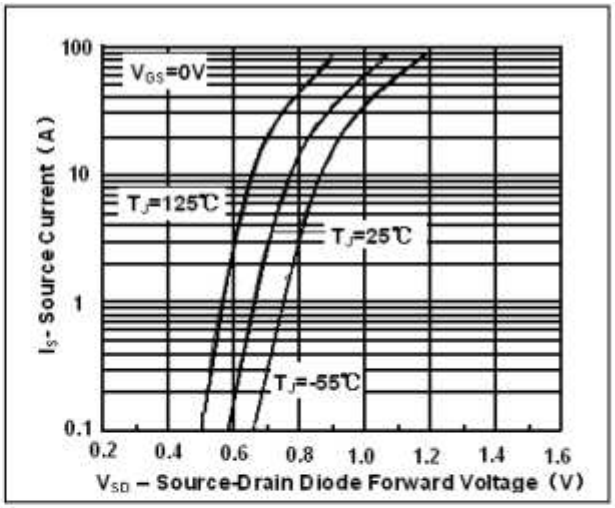


Figure 6,Source-Drain Diode Forward Voltage

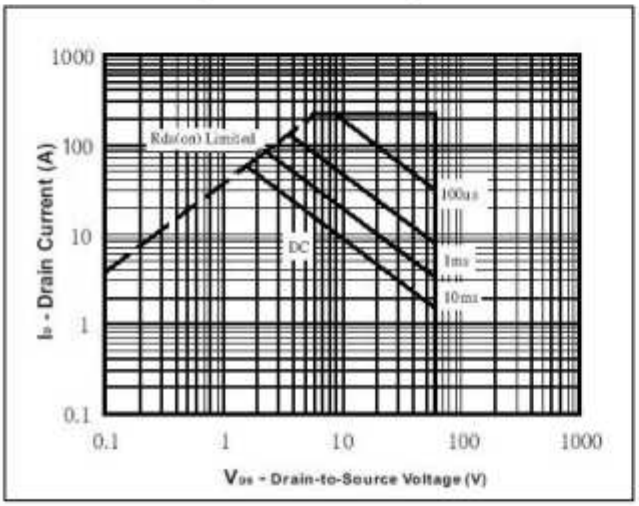


Figure 7. Safe Operation Area

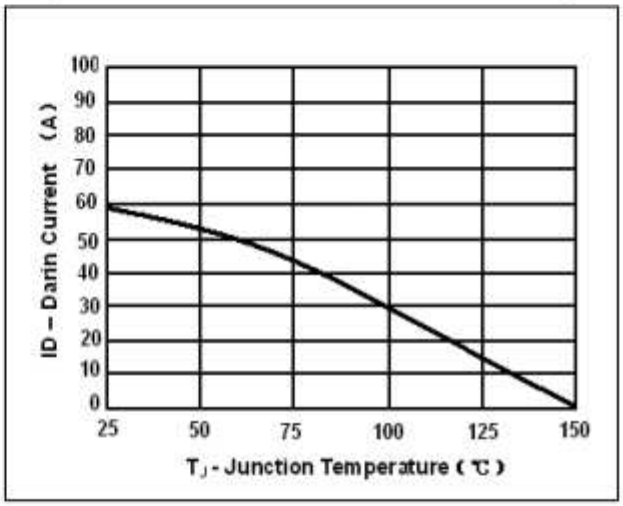


Figure 8. Max Drain Current vs. Junction Temperature

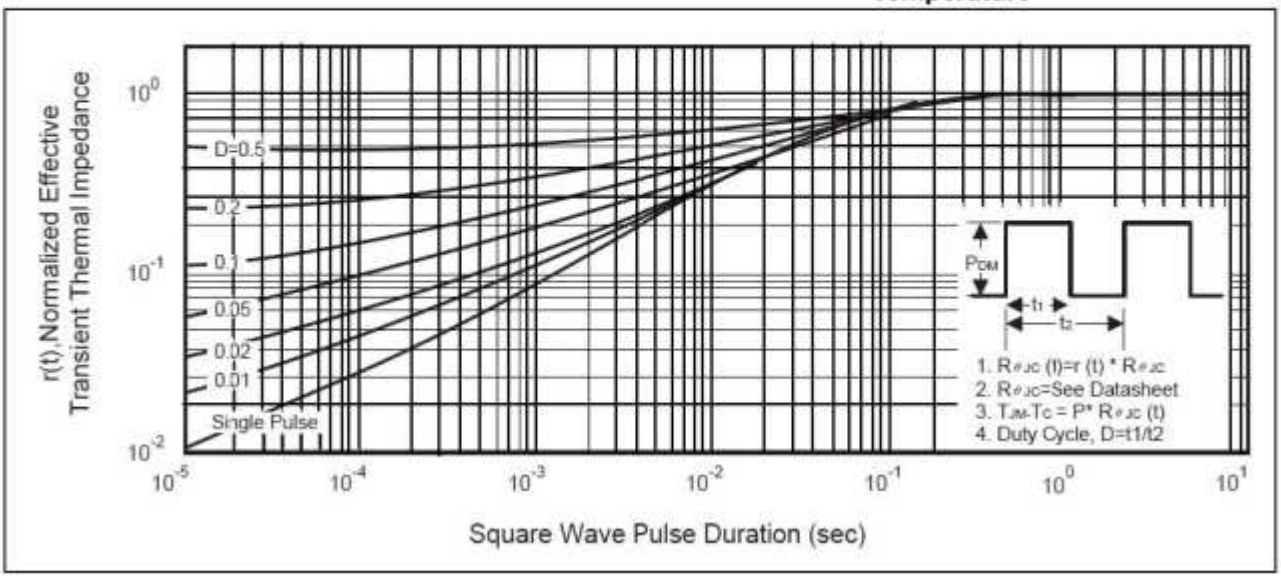
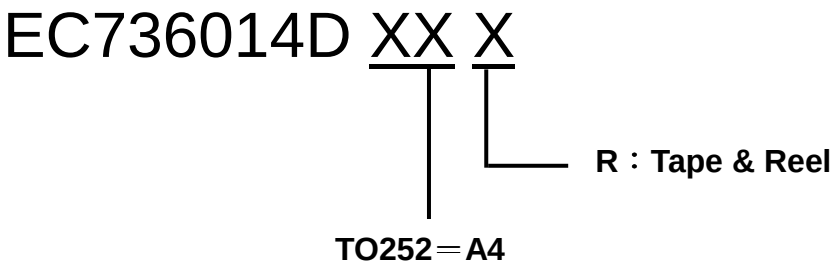


Figure 9. Transient Thermal Impedance Curve

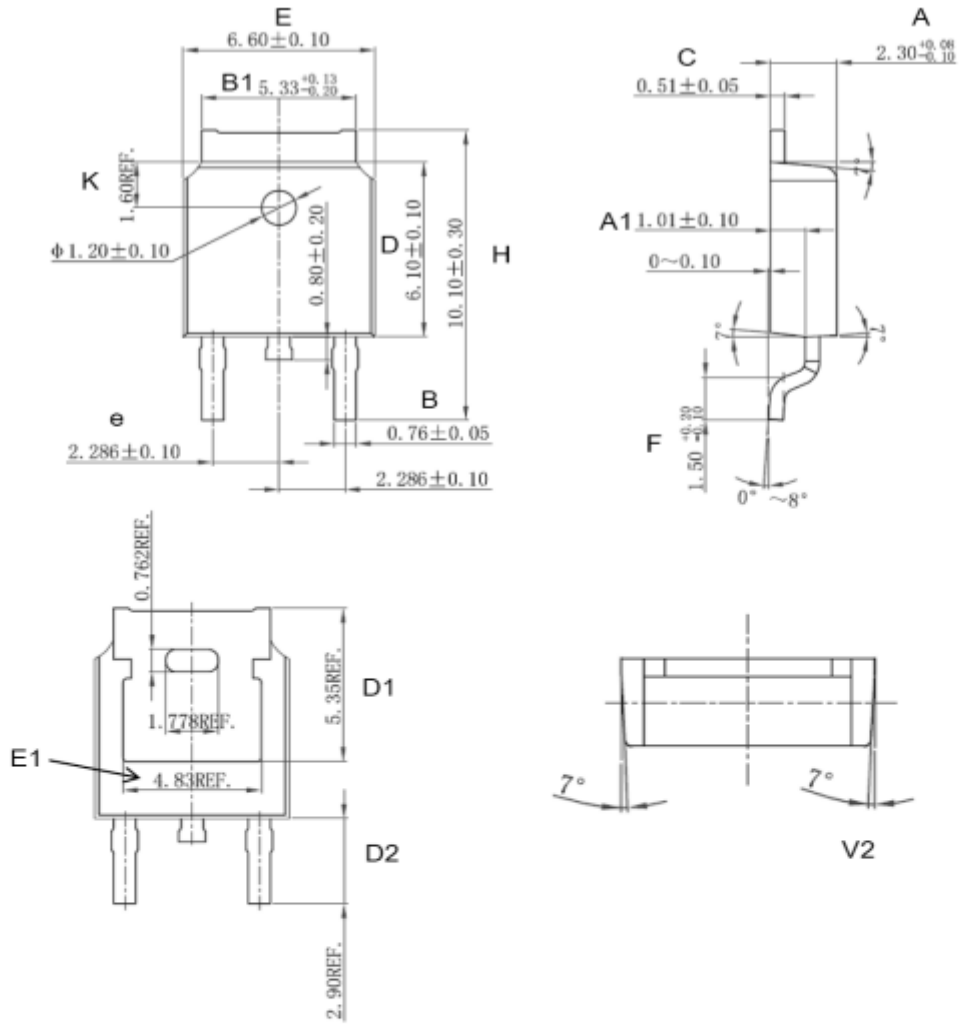
Ordering and Marking Information



Part Number	Package	Marking	Marking Information
EC736014DA4R	TO252		

Package Outline Dimension

DPAK PACKAGE OUTLINE DIMENSION



Symbol	Dimension In Millimeters			Dimension In Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.200	2.300	2.380	0.087	0.091	0.094
A1	0.910	1.010	1.110	0.036	0.040	0.044
B	0.710	0.760	0.810	0.028	0.030	0.032
B1	5.130	5.330	5.460	0.202	0.210	0.215
C	0.460	0.510	0.560	0.018	0.020	0.022
D	6.000	6.100	6.200	0.236	0.240	0.244
D1	5.350 (REF)			0.211 (REF)		
D2	2.900 (REF)			0.114 (REF)		
E	6.500	6.600	6.700	0.256	0.260	0.264
E1	4.83 (REF)			0.190 (REF)		
e	2.186	2.286	2.386	0.086	0.090	0.094
H	9.800	10.100	10.400	0.386	0.398	0.409
F	1.400	1.500	1.700	0.055	0.059	0.067
K	1.600 (REF)			0.063 (REF)		
V2	8^0 (REF)			8^0 (REF)		